

### **ABSTRACT OF THE DISCLOSURE**

5       The invention relates to a power semiconductor module mounted with a base  
plate or directly mounted on a heat sink, including a packaging, at least one power  
semiconductor component and at least one substrate provided on both sides with a  
metallic layer. The at least one power semiconductor component is arranged on the  
first metallic layer. The second metallic layer is arranged on the second main  
10       surface of the substrate. On the first main surface of the substrate an additional  
conductive layer is arranged around the edge of the substrate and is  
electroconductively connected with the metallic layer on the second main surface of  
the substrate.